CX18 NO CLEAN CORED WIRE SOLDER

FEATURES

- Fast Wetting
- Minimal/Clear Residue
- Extends Solder Tip Life
- ROL0 per IPC J-STD-004
- REACH and RoHS Compliant*
- Low Odor / Fumes

DESCRIPTION

CX18 is a no clean flux core wire solder designed to offer excellent soldering results with all alloys and on all surface finishes. Engineered for high operator satisfaction CX18 is a low odor/smoke formula which promotes thermal transfer, and fast wetting without the need for additional flux. CX18 post solder residues are minimal, clear and pass IPC-004A and IPC-004B SIR and corrosion requirements.

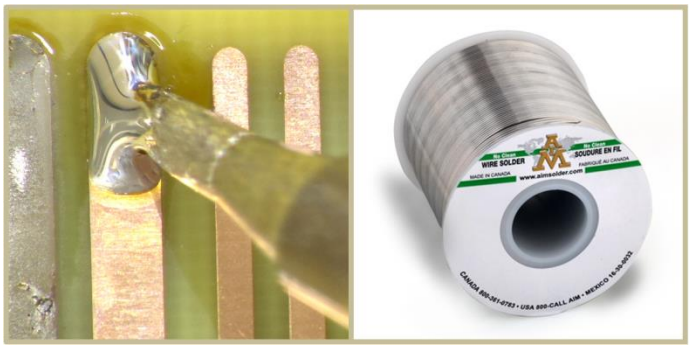
STANDARD AVAILABILITY

CX18 is available in multiple lead-free alloys. Additional alloys and diameters may be available upon request.

APPLICATION

Best results are obtained with a properly sized solder iron tip at a temperature between 300° - 400°C (575° - 750°F) for leaded alloys and 370° - 425°C (700° - 800°F) for lead-free alloys. If additional flux is required AIM NC280 liquid flux or NC217 gel flux are recommended.

*Lead-free.



HANDLING & STORAGE

Time	Parameters
7 Years	< 85°F (< 29°C)

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

CLEANING

CX18 can be cleaned with commercially available flux removers. IPA is not recommended. Contact AIM for specific information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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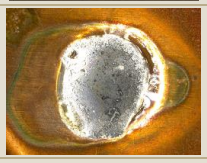
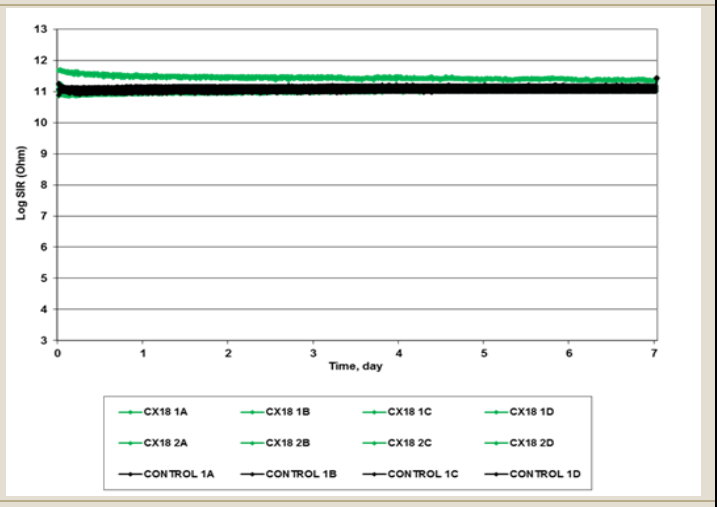
TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROL0	
IPC Flux Classification	J-STD-004B 3.3.1	ROL1	
Name	**Test Method**	**Typical Results**	**Image**
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.09% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	PASS
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	156 mg KOH/g flux Typical	

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